Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.5 EP)
Lead Count	20
Terminal Finish	NiPdAu
MS Number	MS010714B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.74E-02	83.25	832500	47.09	470913
Thermosets	Epoxy resin	Proprietary	1.13E-03	5.42	54200	3.07	30659
Thermosets	Phenol resin	Proprietary	7.20E-04	3.45	34500	1.95	19515
Other inorganic materials	Metal Hydroxide	Proprietary	1.13E-03	5.42	54200	3.07	30659
Others	Others	Proprietary	5.13E-04	2.46	24600	1.39	13915
Subtotal			2.09E-02	100.00	1000000	56.57	565661

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.44 E-02	97.50	975000	38.89	388942
Copper & its alloys	Iron	7439-89-6	3.46 E-04	2.35	23500	0.94	9375
Copper & its alloys	Zinc	7440-66-6	1.77 E-05	0.12	1200	0.05	479
Copper & its alloys	Phosphorus	7723-14-0	4.42 E-06	0.03	300	0.01	120
Subtotal			1.47 E-02	100.00	1000000	39.89	398915

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	3.55 E-04	97.3	972697	0.96	9623
Precious metals	Palladium	7440-05-3	8.26 E-06	2.3	22621	0.02	224
Precious metals	Gold	7440-57-5	1.71 E-06	0.5	4683	0.005	46
Subtotal			3.65 E-04	100.00	1000000	0.99	9893

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	7.77 E-05	99.0	990000	0.211	2106
Precious Metals	Palladium	7440-05-3	7.85 E-07	1.0	10000	0.002	21
Subtotal			7.85 E-05	100.0	1000000	0.21	2128

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.48 E-04	100.0	1000000	1.76	17552

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.66 E-04	77.00	770000	0.45	4505
Other organic materials	Acrylic resin	Proprietary	1.51 E-05	7.00	70000	0.04	410
Other organic materials	Acrylate	Proprietary	1.19 E-05	5.50	55000	0.03	322
Other organic materials	Polybutadiene derivative	Proprietary	9.72 E-06	4.50	45000	0.03	263
Thermoset	Epoxy resin	Proprietary	5.40 E-06	2.50	25000	0.01	146
Other organic materials	Butadiene Copolymer	Proprietary	3.24 E-06	1.50	15000	0.01	88
Others	Additive	Proprietary	3.24 E-06	1.50	15000	0.01	88
Others	Peroxide	Proprietary	1.08 E-06	0.50	5000	0.003	29
Subtotal			2.16 E-04	100.0	1000000	0.59	5851

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.69 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.5 EP)
Lead Count	20
Terminal Finish	100 Sn
MS Number	MS010587B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	9.63E-03	86.91	869100	26.11	261091
Thermosets	Epoxy & Phenol Resin	Proprietary	1.42E-03	12.78	127800	3.84	38393
Other inorganic materials	Carbon black	1333-86-4	3.44E-05	0.31	3100	0.09	931
Subtotal			1.11 E-02	100.00	1000000	30.04	300415

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.00 E-02	97.5	975000	54.30	543048
Copper & its alloys	Iron	7439-89-6	4.83 E-04	2.35	23500	1.31	13089
Copper & its alloys	Zinc	7440-66-6	2.47 E-05	0.12	1200	0.07	668
Copper & its alloys	Phosphorus	7723-14-0	6.17 E-06	0.03	300	0.02	167
Subtotal			2.06 E-02	100.00	1000000	55.70	556972

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.61 E-04	100.0	1000000	1.25	12498

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.04 E-04	100.0	1000000	1.91	19088

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.49 E-04	99.0	990000	0.94	9449
Precious metals	Palladium	7440-05-3	3.52 E-06	1.0	10000	0.01	95
Subtotal			3.52 E-04	100.0	1000000	0.95	9544

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.02 E-03	100.0	1000000	8.18	81807

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.67 E-04	77.71	777100	1.54	15363
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	2.27 E-05	3.11	31100	0.06	615
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	2.27 E-05	3.11	31100	0.06	615
Other organic materials	Butyrolactone, gamma-	96-48-0	2.27 E-05	3.11	31100	0.06	615
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	2.27 E-05	3.11	31100	0.06	615
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	2.27 E-05	3.11	31100	0.06	615
Other organic materials	Organosilane	TS ref# 10001	2.27 E-05	3.11	31100	0.06	615
Other inorganic materials	Copper(II) oxide	1317-38-0	2.27 E-05	3.11	31100	0.06	615
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.79 E-06	0.52	5200	0.010	103
Subtotal			7.30 E-04	100.0	1000000	1.98	19770

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.69 E-02**	**100**	**1000000**

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ANALOG DEVICES